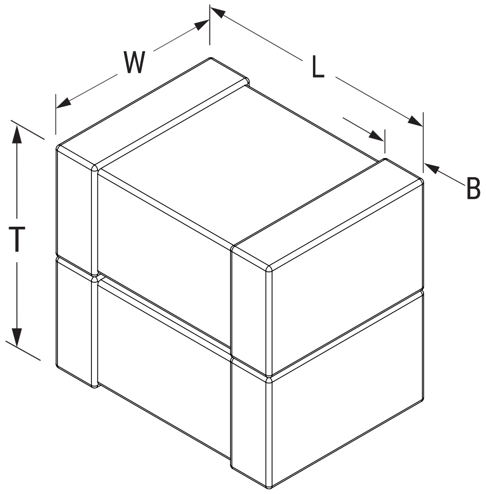
CKC18C303KDGLCTU

KONNEKT KC-LINK Comm C0G, Ceramic, 0.03 uF, 10%, 1,000 VDC, C0G, 2-Chip Standard Orientation.



Click here for the 3D model.

General Information	
Series	KONNEKT KC-LINK Comm C0G
Style	KONNEKT
Description	SMD, MLCC, Ultra-Stable, Low Loss, Class I
Features	Ultra-Stable, Low Loss
RoHS	Yes
Termination	Tin
AEC-Q200	No
Typical Component Weight	300 mg
Notes	2-Chip Standard Orientation.
Chip Size	1812-2
MSL	1

Dimensions	
L	4.5mm +/-0.3mm
W	3.2mm +/-0.3mm
T	5.1mm +/-0.4mm
B	0.6mm +/-0.35mm

Packaging Specifications	
Packaging	T&R, 180mm
Packaging Quantity	200

Specifications	
Capacitance	0.03 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	10%
Voltage DC	1000 VDC
Dielectric Withstanding Voltage	1,200 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	C0G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	33.3333 GOhms

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